Product Preview

75 A, 950 V Field Stop Trench IGBT

Trench Field Stop 4th generation Low Vcesat IGBT co-packaged with full current rated diode

Features

- Maximum Junction Temperature : T_J = 175°C
- Positive Temperature Co-efficient for Easy Parallel Operating
- High Current Capability
- Low Saturation Voltage: $V_{CE(Sat)} = 1.31 \text{ V (Typ.)}$ @ $I_C = 75 \text{ A}$
- Fast Switching
- Tighten Parameter Distribution
- These Devices are Pb-Free and are RoHS Compliant

Applications

• Solar Inverter

MAXIMUM RATINGS

Rating	Symbol	Value	Unit	
Collector to Emitter Voltage		V _{CES}	950	V
Gate to Emitter Voltage Transient Gate to Emitter Voltage		V _{GES}	±20 ±30	٧
Collector Current $@T_C = 25^{\circ}C$ $@T_C = 100^{\circ}C$		IC	150 75	Α
Pulsed Collector Current (N	I _{LM}	225	Α	
Pulsed Collector Current (Note 2)		I _{CM}	225	Α
Diode Forward Current $@T_C = 25^{\circ}C$ $@T_C = 100^{\circ}C$		lF	150 75	A
Pulsed Diode Forward Curre	I _{FM}	225	Α	
Maximum Power Dissipation $@T_C = 25^{\circ}C$ $@T_C = 100^{\circ}C$		PD	453 226	W
Operating Junction / Storage Temperature Range		TJ, TSTG	-55 to +175	°C
Maximum Lead Temp. for Soldering Purposes, 1/8" from case for 5 seconds		T _L	300	ů

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. VCC = 700 V, VGE = 15 V, IC = 225 A, RG = 26 Ω , Inductive Load, 100% Tested
- Pulse width limited by max Junction temperature. Defined by design. Not subject to production test

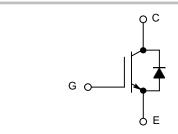
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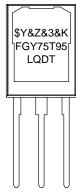
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75 A, 950 V V_{CESat} = 1.31 V (Typ.)





MARKING DIAGRAM



\$Y = ON Semiconductor Logo &Z = Assembly Plant Code &3 = Numeric Date Code &K = 2-Digit Lot Traceability Code

FGY75T95LQDT = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

ORDERING INFORMATION

Part Number	Top Marking	Package	Shipping
FGY75T95LQDT	FGY75T95LQDT	TO-247-3LD (Pb-Free)	30 Units / Rail

THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal resistance junction–to–case, for IGBT	$R_{ heta JC}$	0.33	°C/W
Thermal resistance junction-to-case, for Diode	$R_{ heta JC}$	0.23	°C/W
Thermal resistance junction–to–ambient	$R_{ heta JA}$	40	°C/W

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS		•				
Collector–emitter breakdown voltage, gate–emitter short–circuited	$V_{GE} = 0 \text{ V, } I_C = 1 \text{ mA}$	BVCES	950			V
Temperature Coefficient of Breakdown Voltage	V _{GE} = 0 V, I _C = 1 mA	ΔBVCES ΔΤ _J		0.96		V/°C
Collector-emitter cut-off current, gate- emitter short-circuited	V _{GE} = 0 V, V _{CE} = 950 V	ICES			250	μΑ
Gate leakage current, collector⊡emitter short–circuited	V _{GE} = 20 V , V _{CE} = 0 V	IGES			±400	nA
ON CHARACTERISTICS		1	•	•		
Gate-emitter threshold voltage	$V_{GE} = V_{CE}$, $I_C = 75 \text{ mA}$	VGE(th)	3.4	4.57	6.4	V
Collector-emitter saturation voltage	V _{GE} = 15 V, I _C = 75 A V _{GE} = 15 V, I _C = 75 A, T _J = 175°C	VCE(sat)		1.31 1.52	1.69	V
DYNAMIC CHARACTERISTICS		1	•	•		
Input capacitance	V _{CE} = 30 V, V _{GE} = 0 V, f = 1 MHz	Cies		15400		pF
Output capacitance		Coes		266		
Reverse transfer capacitance		Cres		85.3		
Gate charge total	$V_{CE} = 600 \text{ V}, I_{C} = 75 \text{ V}, V_{GE} = 15 \text{ V}$	Qg		663.3		nC
Gate to emitter charge		Qge		76.1		
Gate to collector charge		Qgc		218.6		
SWITCHING CHARACTERISTICS, INDU	CTIVE LOAD					
Turn-on delay time	T _J = 25°C	td(on)		52.0		ns
Rise time	$V_{CC} = 600 \text{ V, } I_{C} = 37.5 \text{ A}$ $Rg = 4.7 \Omega$	t _r		24.0		
Turn-off delay time	V _{GE} = 15 V Inductive Load	td(off)		496.0		
Fall time	Tilddelive Load	t _f		108.0		
Turn-on switching loss		Eon		2.0		mJ
Turn-off switching loss]	Eoff		1.8		
Total switching loss	1	Ets		3.7		

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
Turn-on delay time	T _J = 25°C	td(on)		52.0		ns
Rise time	$V_{CC} = 600 \text{ V}, I_{C} = 75 \text{ A}$ $Rg = 4.7 \Omega$	t _r		52.0		
Turn-off delay time	V _{GE} = 15 V	td(off)		476.0		
Fall time	middelive Load	t _f		76.0		
Turn-on switching loss		Eon		4.8		mJ
Turn-off switching loss		Eoff		3.3		-
Total switching loss		Ets		8.1		-
Turn-on delay time	T _J = 175°C	td(on)		44.0		ns
Rise time	$V_{CC} = 600 \text{ V, } I_{C} = 37.5 \text{ A}$ $Rg = 4.7 \Omega$	t _r		30.0		
Turn-off delay time	V _{GE} = 15 V	td(off)		580.0		
Fall time	Inductive Load	t _f		144.0		
Turn-on switching loss		Eon		3.8		mJ
Turn-off switching loss		Eoff		2.7		
Total switching loss		Ets		6.5		-
Turn-on delay time	T _J = 175°C	td(on)		48.0		ns
Rise time	$V_{CC} = 600 \text{ V, } I_C = 75 \text{ A}$ $Rg = 4.7 \Omega$ $V_{GE} = 15 \text{ V}$ Inductive Load	t _r		54.0		_
Turn-off delay time		td(off)		548.0		
Fall time		t _f		118.0		
Turn-on switching loss		Eon		7.6		mJ
Turn-off switching loss		Eoff		5.1		
Total switching loss		Ets		12.7		
DIODE CHARACTERISTICS	·	•	•	•	•	•
Forward voltage	I _F = 75 A I _F = 75 A, T _J = 175°C	V _F		2.03 1.76	2.51	V
Reverse Recovery Energy	T _J = 25°C	E _{rec}		314		uJ
Reverse Recovery Time	$V_R = 600 \text{ V}, I_F = 37.5 \text{ A}$ $dI_F/dt = 1000 \text{ A}/\mu\text{s}$	t _{rr}		105		ns
Reverse Recovery Charge	<u>αιτ</u> , αι = 1000 7 υμο	Q _{rr}		1635		nC
Reverse Recovery Energy	T _J = 25°C	E _{rec}		2390		uJ
Reverse Recovery Time	$V_R = 600 \text{ V}, I_F = 75 \text{ A}$ $dI_F/dt = 1000 \text{ A/}\mu\text{s}$	t _{rr}		259		ns
Reverse Recovery Charge		Q _{rr}		7515		nC
Reverse Recovery Energy	T _J = 175°C	E _{rec}		454		uJ
Reverse Recovery Time	$V_R = 600 \text{ V}, I_F = 37.5 \text{ A}$ $dI_F/dt = 1000 \text{ A}/\mu\text{s}$	t _{rr}		148		ns
Reverse Recovery Charge		Q _{rr}		2436		nC

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise noted)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
Reverse Recovery Energy	T _J = 175°C	E _{rec}		2790		uJ
Reverse Recovery Time	$V_R = 600 \text{ V}, I_F = 75 \text{ A}$ $dI_F/dt = 1000 \text{ A}/\mu\text{s}$	t _{rr}		294		ns
Reverse Recovery Charge		Q _{rr}		9175		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

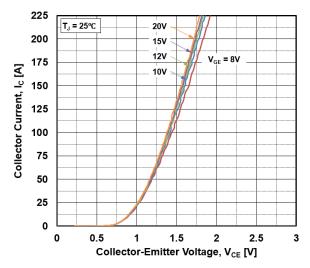


Figure 1. Typical Output Characteristics ($T_J = 25^{\circ}C$)

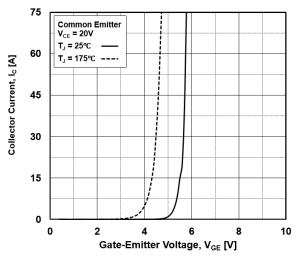


Figure 3. Transfer Characteristics

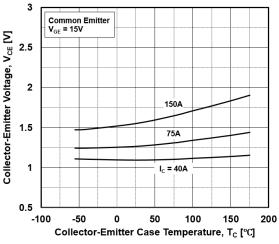


Figure 5. Saturation Voltage vs Case Temperature at Variant Current Level

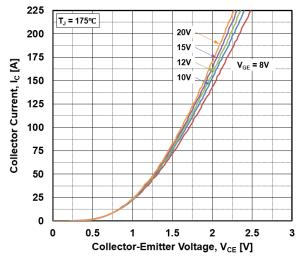


Figure 2. Typical Output Characteristics (T_J = 175°C)

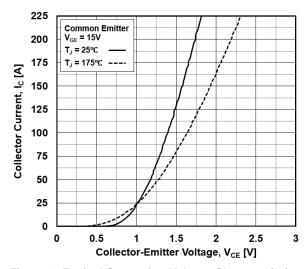


Figure 4. Typical Saturation Voltage Characteristics

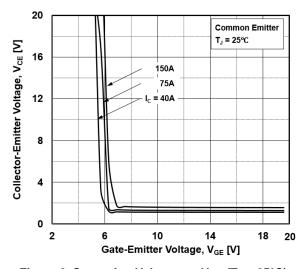


Figure 6. Saturation Voltage vs. V_{GE} (T_J = 25°C)

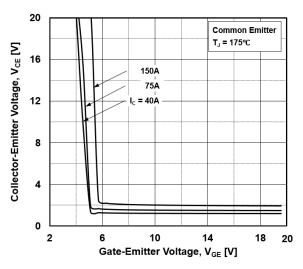


Figure 7. Saturation Voltage vs. V_{GE} (T_J = 175°C)

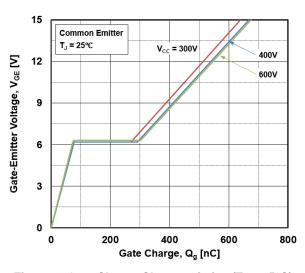


Figure 9. Gate Charge Characteristics ($T_J = 25^{\circ}C$)

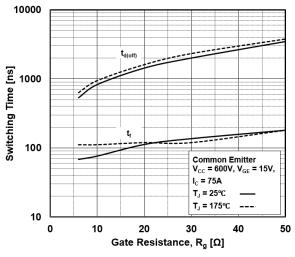


Figure 11. Turn-off Characteristics vs. Gate Resistance

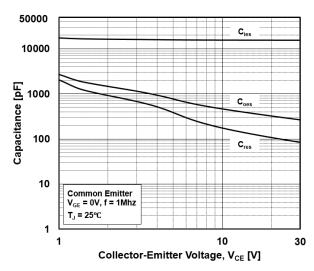


Figure 8. Capacitance Characteristics

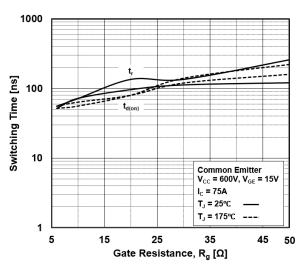


Figure 10. Turn-on Characteristics vs. Gate Resistance

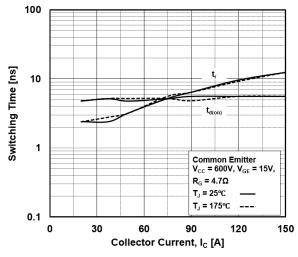


Figure 12. Turn-on Characteristics vs. Collector Current

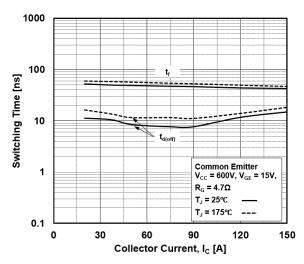


Figure 13. Turn-off Characteristics vs. Collector Current

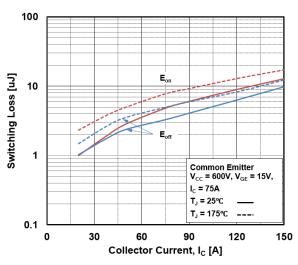


Figure 15. Switching Loss vs. Collector Current

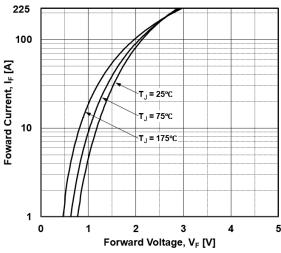


Figure 17. (Diode) Forward Characteristics vs (Normal I–V)

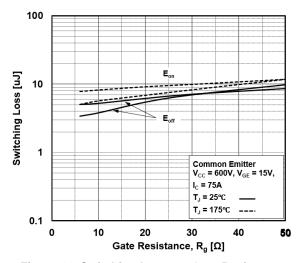


Figure 14. Switching Loss vs. Gate Resistance

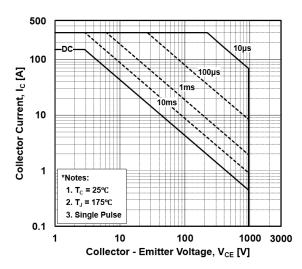


Figure 16. SOA Characteristics (FBSOA)

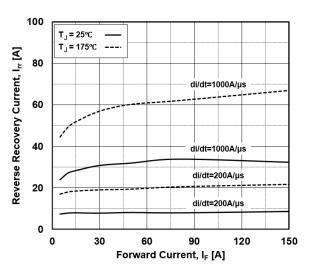
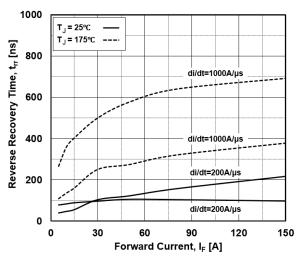


Figure 18. (Diode) Reverse Recovery Current



15000 T_J = 25°C T_J = 175℃ Reverse Recovery Charge, Q_{rr} [nC] 12000 di/dt=1000A/µs 9000 di/dt=1000A/µs 6000 di/dt=200A/µs 3000 di/dt=200A/µs 0 0 30 60 90 120 150 Forward Current, I_F [A]

Figure 19. (Diode) Reverse Recovery Time

Figure 20. (Diode) Stored Charge

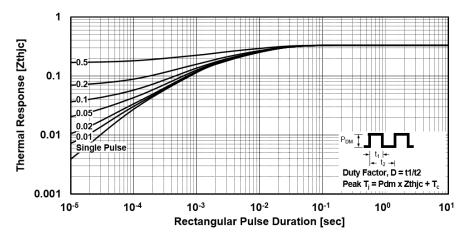


Figure 21. Transient Thermal Impedance of IGBT

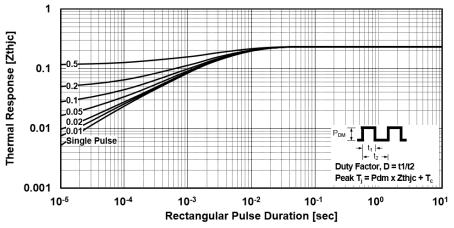


Figure 22. Transient Thermal Impedance of Diode

PACKAGE DIMENSIONS

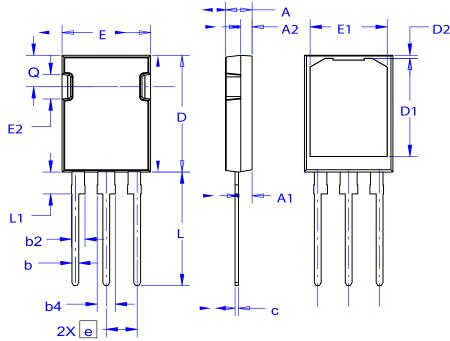


TO-247-3LD CASE 340CD **ISSUE A**

DATE 18 SEP 2018

NOTES:

- A. THIS PACKAGE DOES NOT CONFORM TO ANY STANDARDS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS MOLD FLASH AND TIE BAR PROTRUSIONS.
- D. DIMENSION AND TOLERANCE AS PER ASME Y14.5-2009.



DIM	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	4.58	4.70	4.82	
A1	2.20	2.40	2.60	
A2	1.80	2.00	2.20	
D	20.32	20.57	20.82	
Е	15.37	15.62	15.87	
E2	4.12	4.32	4.52	
е	~	5.45	~	
L	19.90	20.00	20.10	
L1	3.69	3.81	3.93	
Q	5.34	5.46	5.58	
b	1.10	1.20	1.30	
b2	2.10	2.24	2.39	
b4	2.87	3.04	3.20	
С	0.51	0.61	0.71	
D1	16.63	16.83	17.03	
D2	0.51	0.93	1.35	
E1	13.40	13.60	13.80	

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